Certificate of Compliance

DUNS	Document Date	URL for Additional Information
00-489-5751	**Sep 26, 2014 03:10 AM**	Fairchildsemi.com

Contact	Title	Phone	Email
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Material Declaration Processing Information

FSID	Material Declaration	Site Owner	Assembly Location	Package Weight(g)	MSL Rating
SB130	**DO41-2 (Plastic).csv**	PANJIT	PANJIT	**0.336517**	**NA**

Terminal Finish	Base Alloy	Green Status	Reflow Cycles	Max Time at Temp	Peak Temp
Sn	Other	This product is not green as defined by Fairchild's Green Policy. Please use this link to access Fairchild's Green Product Definition. Fairchild's Green Policy	Not Applicable		Not Applicable

RoHS Declaration

The European Parliament and of the Council on the Restriction of the use of Certain Hazardous Substances in Electrical and Electronic Equipment (RoHS) directive restricts the concentration of Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) to 0.1% (1000 PPM) and restricts the concentration of Cadmium (Cd) to 0.01% (100 PPM) in homogeneous materials of electronic products.

The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU.

Exemptions as declared for the directive are:

7(a) Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).

China RoHS

With the possible exception of lead, if applicable (refer to the RoHS Declaration statement above), this product and all homogeneous materials in the product comply with the China RoHS standard SJ/T 11363-2006.

REACH Compliance

European Union Regulation (EC) No 1907/2006 concerning the Registration, Evaluation, Authorization, and Restriction of Chemicals (REACH) entered into force on June 1, 2007. Fairchild Semiconductor agrees with the purpose of REACH, which is to ensure a high level of protection of human health and the environment. Fairchild semiconductor is compliant with all applicable requirements of REACH and upon request will provide information regarding the chemical composition of our products.

Fairchild Semiconductor is neither a manufacturer nor importer of mixtures into Europe and therefore the registration requirements of REACH do not apply to us. It is expected that any electronic materials manufacturer that uses mixtures from Europe in their products will ensure compliance with REACH registration requirements.

Product (articles) manufacturers or importers into Europe are obligated under Article 33 of REACH to inform recipients of any articles that contain chemicals on the Substances of Very High Concern (SVHC) candidate list above a 0.1% concentration (by weight per article). If this contains substances on the REACH SVHC candidate list (as published by the ECHA on the following publication dates) in concentrations greater than 0.1%, the SVHC will be listed in the Homogenous Material Declaration Composition listed above:

October 28, 2008; January 13, 2010; March 30, 2010; June 18, 2010; December 15, 2010; June 20, 2011; December 19, 2011; June 18, 2012*; December 19, 2012; June 20, 2013; December 16, 2013; June 16, 2014.

Products manufactured by Fairchild Semiconductor are compliant with the 'Conditions of Restriction' listed in REACH, Annex XVII.

Fairchild Semiconductor will continue to monitor the developments of REACH and is committed to meeting our responsibilities as an environmentally-responsible company. Please refer to the web site below for additional information regarding SVHC:

ECHA European Chemical Agency

* Diboron trioxide was added to REACH Annex XIV as a Substance of Very High Concern(SVHC) on June 18, 2012. Fairchild products in glass encapsulated packages may list Diboron trioxide as a constituent material in the glass encapsulation, in a concentration greater than 0.1%; REACH classifies; glass as a substance of unknown or variable composition, complex reaction products or biological matter (UVCB) containing the elements silica, calcium, sodium, potassium, magnesium and other cautions bonded together with oxygen. In glass, these elements are bonded into a non crystalline molecular structure with completely different properties than the starting material; Therefore Diboron trioxide is not present in the finished Fairchild product and does not require notification of the presents of a SVHC.

The signature below is of the Company's designated personnel with delegated product ecology compliance responsibility and verifies that to the best of our knowledge the statements above are valid and accurate.

David Lancaster

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Environmental Declaration

The content of this document is based upon information collected from Fairchild Semiconductor's supply chain, manufacturing facilities and affiliates worldwide. Providing for limitations below, Fairchild Semiconductor certifies that the information provided in this document is correct as of the date indicated on this page.

Fairchild has implemented systems to ensure products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.

Homogenous Material Composition Declaration

Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification.

Additionally, the following should be noted:

- This statement may not include information regarding the miniscule quantities of dopant and metal materials in the electrical devices contained within the finished product.
- CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Marking Ink	Other Organic Materials	0.2	Supplier		Aluminum	0.03	7429-90-5	89
			Supplier		Padimate	0.02	21245-01-2	59
			Supplier		Silica	0.01	112945-52-5	30
Plating	Other Nonferrous metals & alloys	4.3	Supplier		Tin	4.3	7440-31-5	12778
Silicon Rubber	Other inorganic materials	5.1	Supplier		Silicon	5.1	7440-21-3	15155
Solder Wafer	Other Nonferrous metals & alloys	1.265	A	Lead/Lead Compounds	Lead	1.17	7439-92-1	3477
			Supplier		Silver	0.032	7440-22-4	94
			Supplier		Tin	0.064	7440-31-5	189
Chip	Other inorganic materials	0.88	Supplier		Silicon	0.88	7440-21-3	2615
Encapsulation	Thermoplastics	123.57	B	Antimony/Antimony Compounds	Antimony Trioxide	2.75	1309-64-4	8172
			B	Brominated Flame Retardants (other than PBCs or PBDEs)	Bromine Resin	2.75	6386-73-8	8172
			Supplier		Carbon Black	1.37	1333-86-4	4071
			Supplier		Epoxy Resin	20.6	29690-82-2	61215
			Supplier		Silica, vitreous	96.1	60676-86-0	285573
Lead Wire	Other Ferrous alloys, non-stainless steels	201.201	Supplier		Copper	201	7440-50-8	597296
			Supplier		Iron	0.161	7439-89-6	478
			Supplier		Phosphorus	0.04	7723-14-0	119
Marking Ink	Other Organic Materials	0.2	Supplier		2-Propenoic acid polymer	0.13	53192-18-0	386
			Supplier		additive	0.01	947-19-3	30